SLPC2026

The 6th Smart Laser Processing Conference

Co-organized by Joining and Welding Research Institute (JWRI),
The University of Osaka, Japan

Date April 21-23, 2026 **Venue** Pacifico Yokohama, Japan

Co-located with OPIC2026 -OPTICS & PHOTONICS International Congress 2026 (April 20-24, 2026)

AIM AND SCOPE

Laser beam processing is played an important role in industrial fields of not only macro-products but also micro-products, and its technologies are essential to open the new strategies of smart manufacturing such as highly integrated, accurate, efficient processing with low energy consumption.

SLPC2026 deals with science and technology of smart laser materials processing including micro and macro laser processing. SLPC2026 is planned as a three-day event with a plenary session, oral session and poster session.

The aim of this conference is to provide a forum for discussion of fundamental aspects of laser-matter interaction, the state-of-the-art of smart laser processing, and topics for the next generation with fundamental scientists, end users and laser manufacturers.

We expect that SLPC2026 would play an important role not only for understanding fundamental knowledge of laser processing but also forecasting future technologies and the future laser processing fields.

Also, during the SLPC2026 conference, OPTICS & PHOTONICS International Congress 2026 (OPIC2026) will be held jointly in the same venue. SLPC2026 attendees can join the other conferences of OPIC2026 free of charge since SLPC2026 is one of the conferences of OPIC2026. SLPC2026 registration will be available at the OPIC2026 website; https://opicon.jp/

Conference Chair: Prof. **Masahiro Tsukamoto**, JWRI, The University of Osaka, Japan
Steering Committee Chair: Dr. **Yuji Sato**, JWRI, The University of Osaka , Japan
Program Committee Chair: Prof. **Masaki Hashida**, Tokai University; Kyoto University, Japan

TOPICS AND FIELDS

- Cutting
- Welding
- Additive Manufacturing / Selective Laser Melting
- Cladding / Laser Metal Deposition
- Functional Surface Manufacturing
- Laser Peening and Related Phenomena
- Laser Polishing / Cleaning
- Short Wavelength Application
- Micro Nano Processing
- Ultrashort Pulsed Laser Processing
- Advanced Lasers and Optical Technologies
- CFRP Processing
- Industrial Applications
- AI / CPS Laser Processing
- High Power Blue and Green Lasers
- Others

CONTACT

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